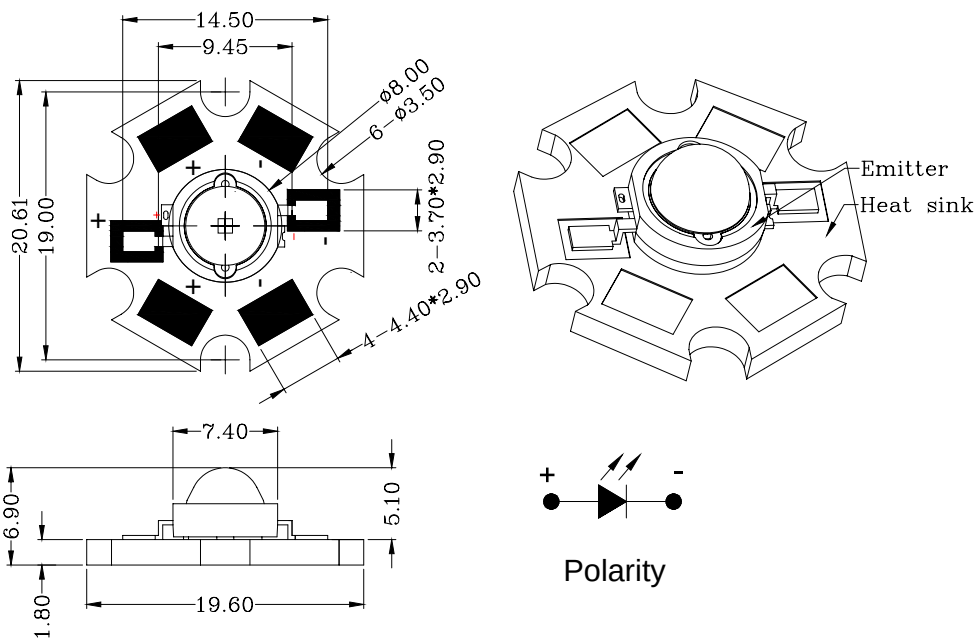
● Features:

1. Input power: 1W.
2. Chip material: InGaN, Flip chip.
3. Emitted color: White.
4. High lumen output.
5. High flux density.
6. Low power consumption.
7. Efficient heat transfer.
8. With heat sink.

● Applications:

1. Torch.
2. Head Light.
3. Architectural Lighting.
4. LCD Backlight.

● Package dimensions：



Notes:

1. All dimensions are in millimeters.
2. Tolerance is ±0.5mm unless otherwise specified.

● Absolute maximum ratings(T_J=25℃)

Parameter	Symbol	Rating	Unit
Power Dissipation	P_D	1.0	W
DC Forward Current*[1]	I_F	350	mA
Peak Pulsed Forward Current*[2]	I_{FP}	1.0	A
LED Junction Temperature	T_J	130	°C
Operating Temperature	Topr	-30~120	°C
Storage Temperature	Tstg	-40~120	°C
Reverse Voltage	V_R	5	V
Soldering Temperature (T=5 sec)	Tsol	300 ± 5	°C

*[1]Proper current derating must be followed to keep LED junction temperature (T_J) below the maximum.

*[2]Condition for I_{FP} is pulsed with 1/10 duty and 0.1msec width.

● Electrical & Optical Characteristics (T_J=25℃)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	I_F =350mA	-	3.5	4.0	V
Total Flux	Φ_v	I_F =350mA	25	35	-	lm
Color Temperature	CCT	I_F =350mA	5000	6500	8000	K
Reverse Current	I_R	V_R=5V	-	-	50	μA
Thermal Resistance, Junction To Case	$R\theta_{J-C}$	I_F =350mA	-	15	-	℃/W
Viewing Angle	$2\theta_{1/2}$	I_F =350mA	-	140	-	degree
Chromaticity Coordinates	x	I_F =350mA	-	0.32	-	
	y	I_F =350mA	-	0.31	-	

Typical electro-optical characteristics curves

Fig.1 RELATIVE INTENSITY VS. WAVELENGTH

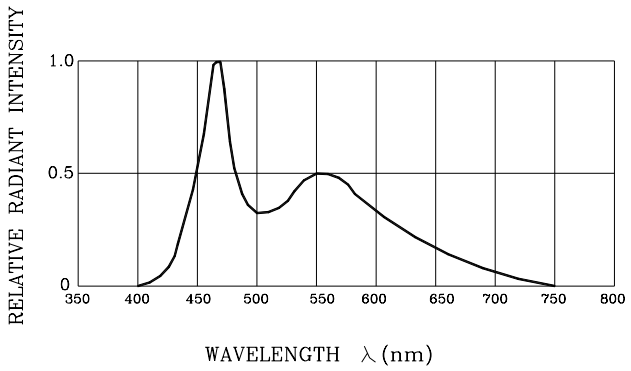


Fig.2 FORWARD CURRENT VS. AMBIENT TEMPERATURE

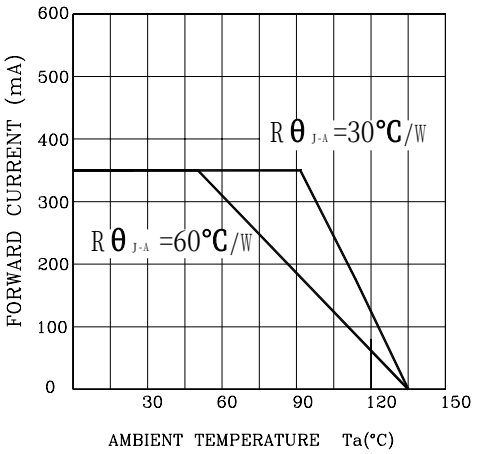


Fig.3 FORWARD CURRENT VS. FORWARD VOLTAGE

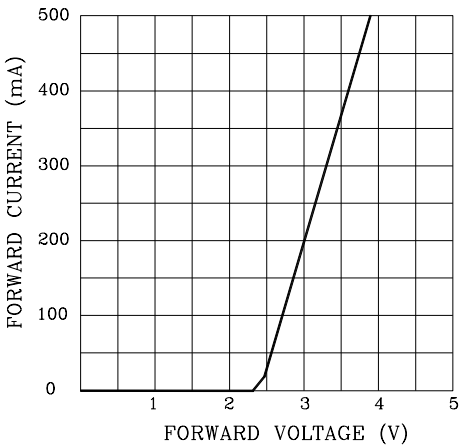


Fig.4 RELATIVE LUMINOUS INTENSITY VS. JUNCTION TEMPERATURE

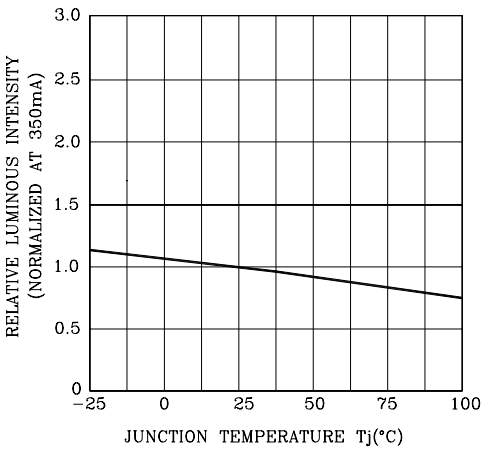


Fig.5 RELATIVE LUMINOUS INTENSITY VS. FORWARD CURRENT

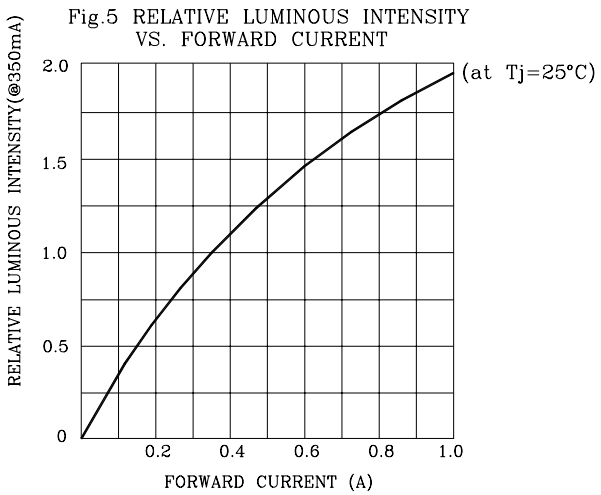
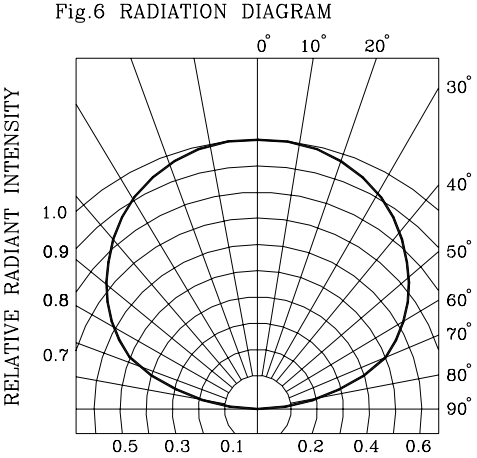
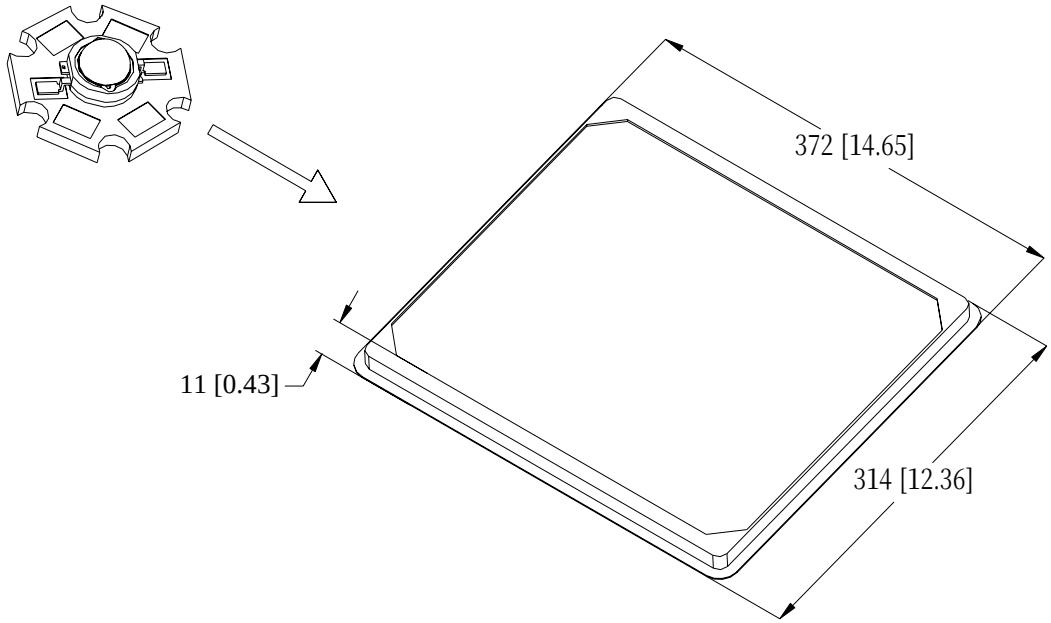


Fig.6 RADIATION DIAGRAM

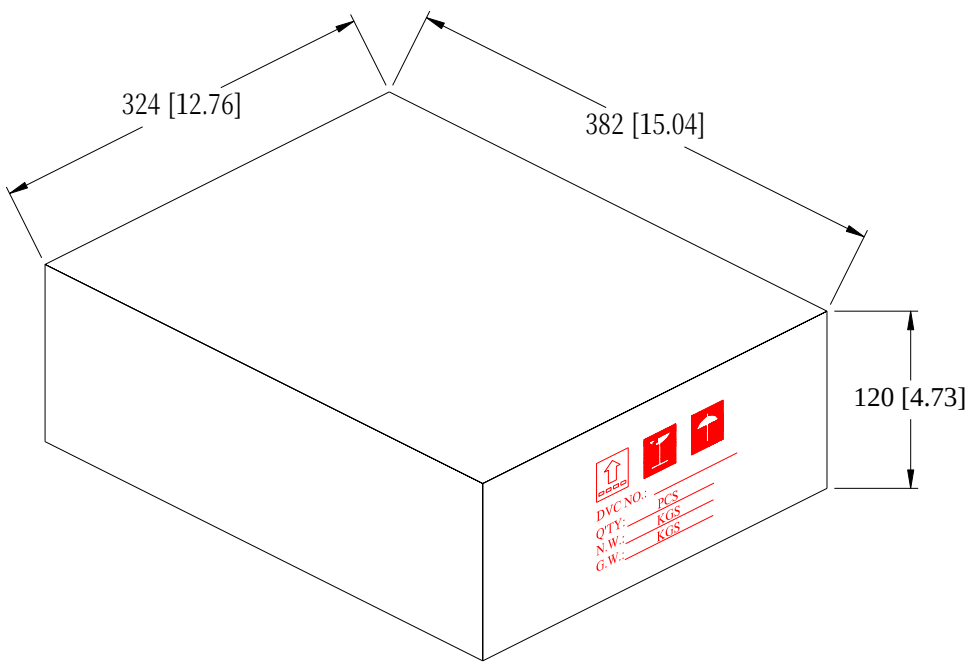


● Package Method : (unit:mm)



80 pcs/tray

Tray



10 tray / carton

Carton

NOTES : Tray : Tolerance is ± 5 mm unless otherwise noted.
Carton : Tolerance is ± 10 mm unless otherwise noted.

● Total Flux Bin Limits (At 350mA)

BIN CODE	Min. (lm)	Max. (lm)
K	25	33
L	33	42
M	42	55

Tolerance for each Bin limit is ± 15 %

● Color Temperature Bin Limits(At 350mA)

BIN CODE	Min. (K)	Max. (K)
4	5000	6000
5	6000	7000
6	7000	8000

Tolerance for each Bin limit is ± 500 K

● BIN : x x

Notes:

1. Bin categories are established for classification of products. Products may not be available in all bin categories.

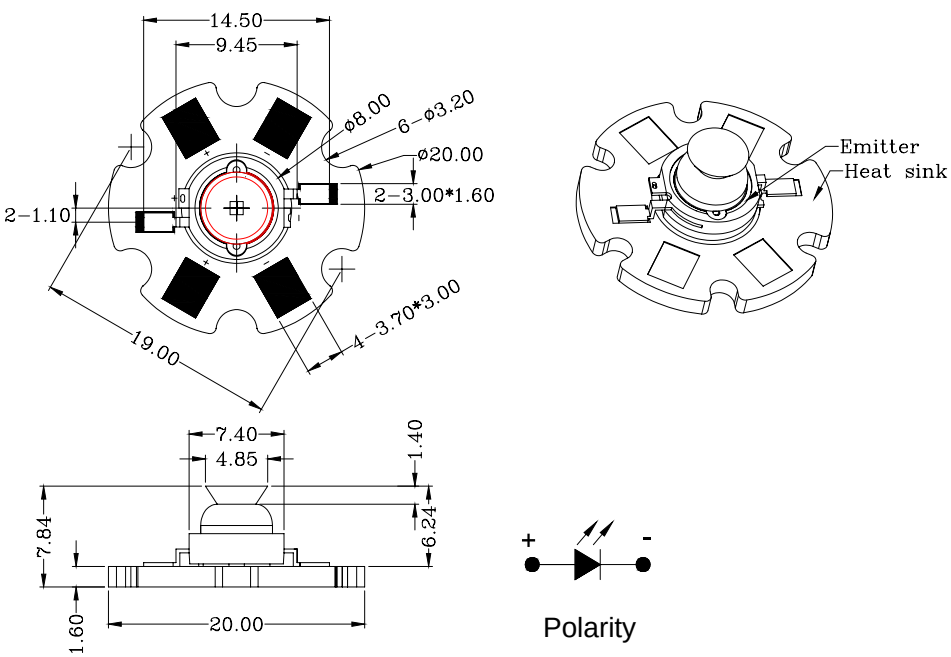
● Features:

1. Input power: 1W.
2. Chip material: AlInGaN.
3. Emitted color: White.
4. High lumen output.
5. High flux density.
6. Low power consumption.
7. Efficient heat transfer.

● Applications:

1. Light engine.
2. Torch.
3. Desk lamp.
4. General lighting.

● Package dimensions：



Notes:

1. All dimensions are in millimeters.
2. Tolerance is ±0.5mm unless otherwise specified.

● Absolute maximum ratings(Ta=25℃)

Parameter	Symbol	Rating	Unit
Power Dissipation	P_D	1.0	W
DC Forward Current*[1]	I_F	350	mA
Peak Pulsed Forward Current*[2]	I_{FP}	1.0	A
LED Junction Temperature	T_j	130	°C
Operating Temperature	Topr	-30~120	°C
Storage Temperature	Tstg	-40~120	°C
Reverse Voltage	VR	5	V
Soldering Temperature (T=5 sec)	Tsol	300 ± 5	°C

*[1]Proper current derating must be followed to keep LED junction temperature (T_j) below the maximum.

*[2]Condition for I_{FP} is pulsed with 1/10 duty and 0.1msec width.

● Electrical & Optical Characteristics LED (Ta=25℃)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	I_F = 350mA	-	3.5	4.0	V
Total Flux	Φ_v	I_F = 350mA	20	25	-	lm
Color Temperature	CCT	I_F = 350mA	5000	6500	8000	K
Color Rendering Index	CRI	I_F = 350mA	80	-	-	
Reverse Current	I_R	5V	-	-	50	μA
Thermal Resistance, Junction To Case	$R\theta_{J-C}$	T_J = 25℃, I_F = 350mA	-	15	-	℃/W
Viewing Angle	θpeak	I_F = 350mA	-	75-85	-	degree
Chromaticity Coordinates	x	I_F = 350mA	-	0.32	-	
	y	I_F = 350mA	-	0.31	-	

Typical electro-optical characteristics curves

Fig.1 RELATIVE INTENSITY VS. WAVELENGTH

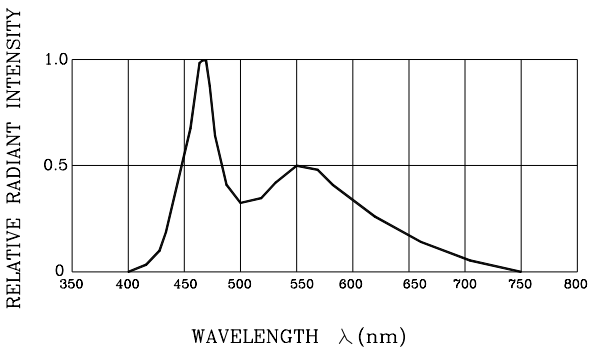


Fig.2 FORWARD CURRENT DERATING CURVE

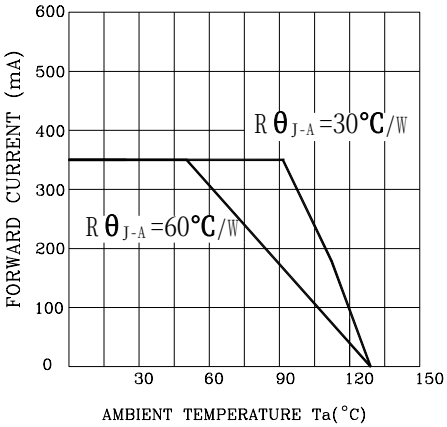


Fig.3 FORWARD CURRENT VS. FORWARD VOLTAGE

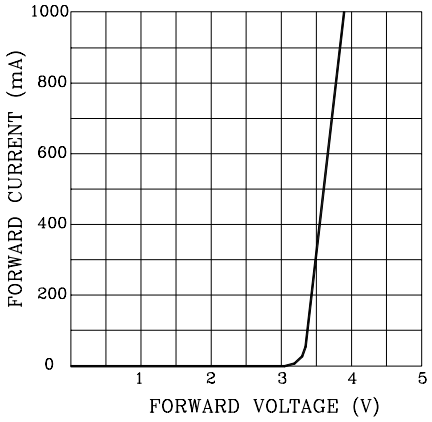


Fig.4 RELATIVE LUMINOUS INTENSITY VS. AMBIENT TEMPERATURE

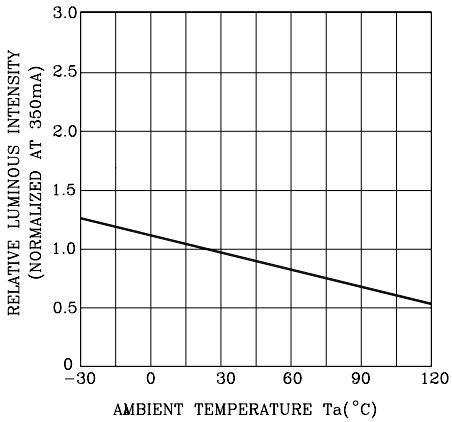


Fig.5 RELATIVE LUMINOUS INTENSITY VS. FORWARD CURRENT

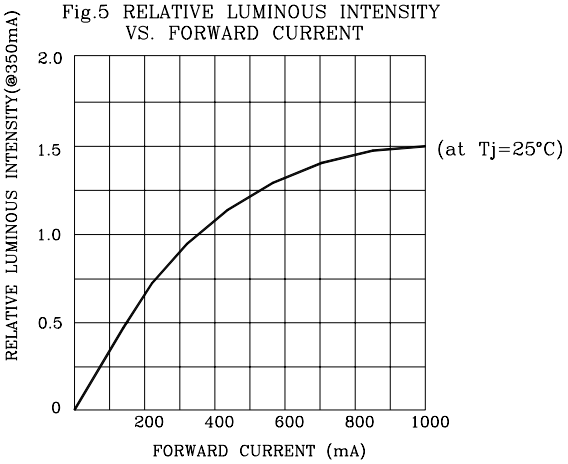
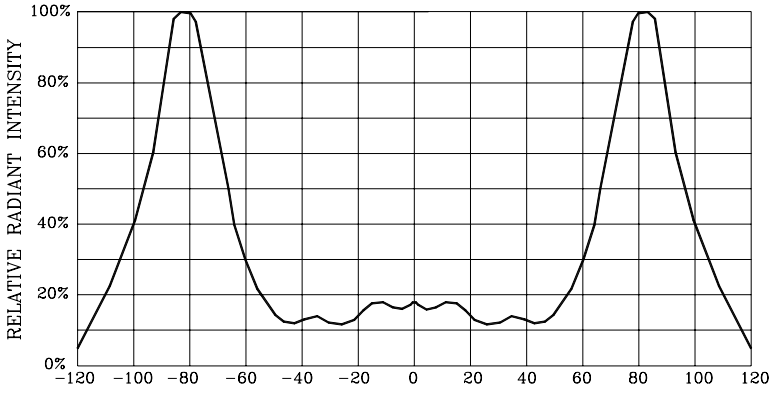
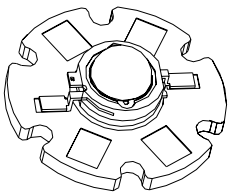
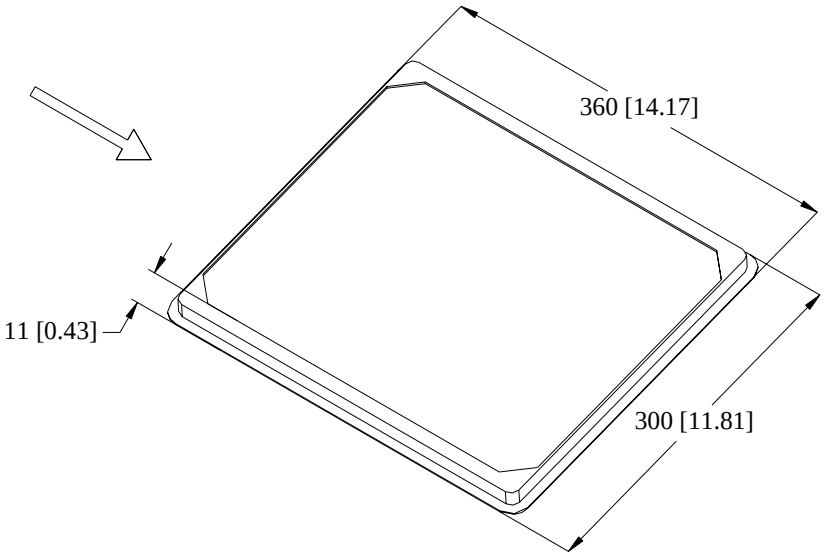


Fig.6 RADIATION DIAGRAM



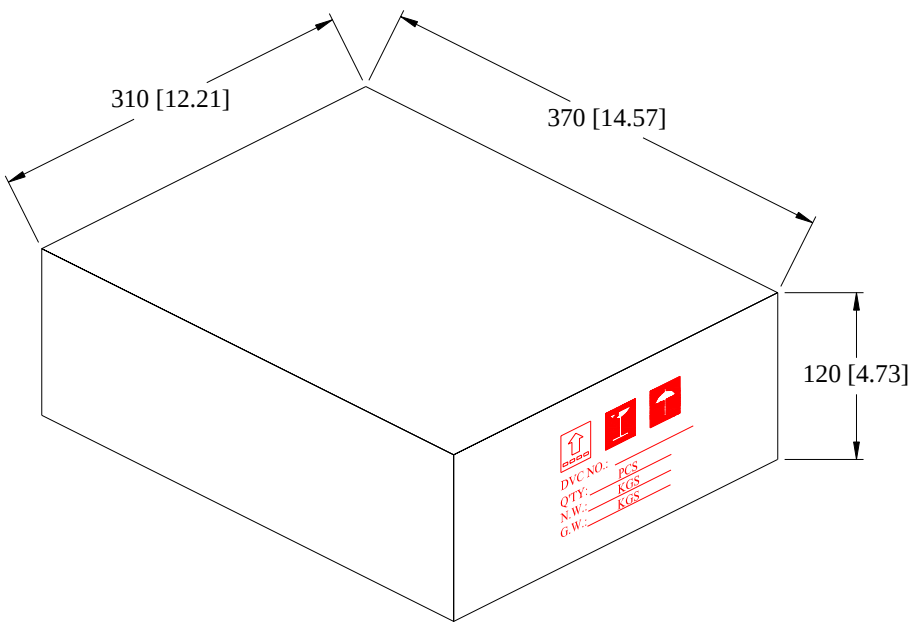
● Package Method : (unit:mm)





80 pcs/tray

Tray



10 tray / carton

Carton

NOTES : Tray : Tolerance is ± 5 mm unless otherwise noted.
Carton : Tolerance is ± 10 mm unless otherwise noted.

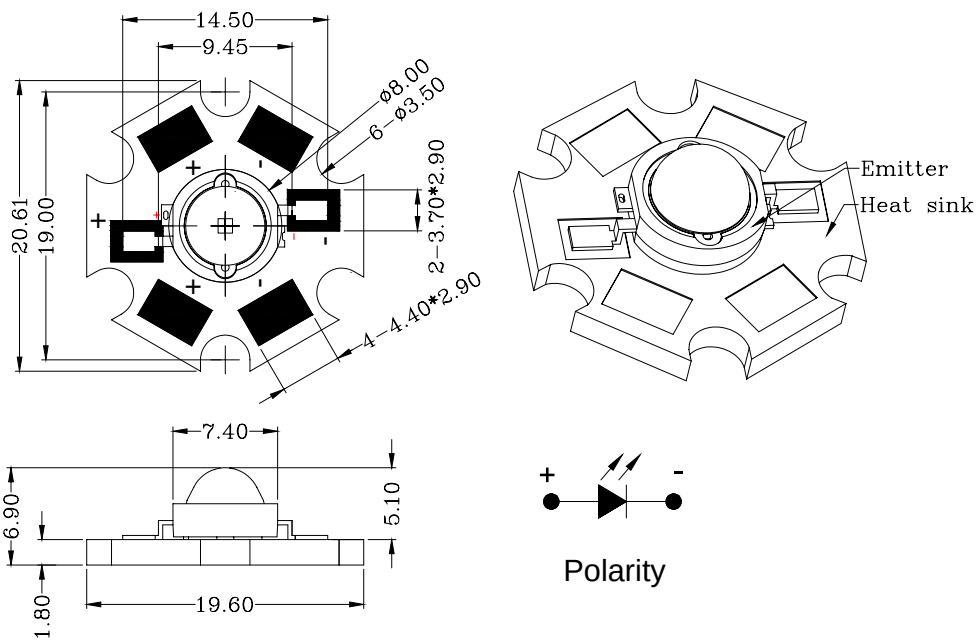
● Features:

1. Input power: 1W.
2. Chip material: AlInGaN, Flip chip.
3. Emitted color: Green.
4. High lumen output.
5. High flux density.
6. Low power consumption.
7. Efficient heat transfer.
8. With heat sink.

● Applications:

1. Torch.
2. Head Light.
3. Architectural Lighting.
4. LCD Backlight.

● Package dimensions：



Notes:

1. All dimensions are in millimeters.
2. Tolerance is ±0.5mm unless otherwise specified.

● Absolute maximum ratings(T_J=25℃)

Parameter	Symbol	Rating	Unit
Power Dissipation	P_D	1.0	W
DC Forward Current*[1]	I_F	350	mA
Peak Pulsed Forward Current*[2]	I_{FP}	1.0	A
LED Junction Temperature	T_J	130	°C
Operating Temperature	Topr	-30~120	°C
Storage Temperature	Tstg	-40~120	°C
Reverse Voltage	V_R	5	V
Soldering Temperature (T=5 sec)	Tsol	300 ± 5	°C

*[1]Proper current derating must be followed to keep LED junction temperature (T_J) below the maximum.

*[2]Condition for I_{FP} is pulsed with 1/10 duty and 0.1msec width.

● Electrical & Optical Characteristics (T_J=25℃)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	I_F =350mA	-	3.5	4.0	V
Total Flux	Φ_v	I_F =350mA	25	35	-	lm
Peak Wavelength	λp	I_F =350mA	-	525	-	nm
Dominant Wavelength	λd	I_F =350mA	520	-	530	nm
Spectral Line Half-width	$\Delta \lambda$	I_F =350mA	-	35	-	nm
Reverse Current	I_R	V_R=5V	-	-	50	μA
Thermal Resistance, Junction To Case	$R\theta_{J-C}$	I_F =350mA	-	15	-	℃/W
Viewing Angle	$2\theta_{1/2}$	I_F =350mA	-	140	-	degree

Typical electro-optical characteristics curves

Fig.1 RELATIVE INTENSITY VS. WAVELENGTH

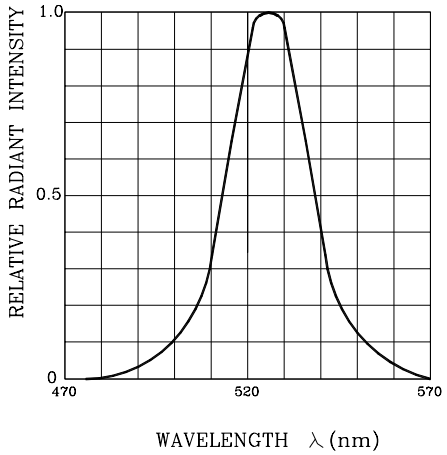


Fig.2 FORWARD CURRENT VS. AMBIENT TEMPERATURE

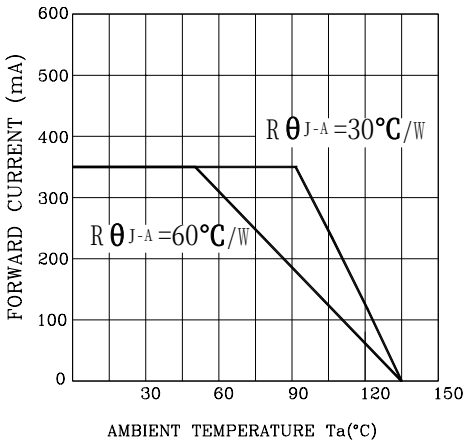


Fig.3 FORWARD CURRENT VS. FORWARD VOLTAGE

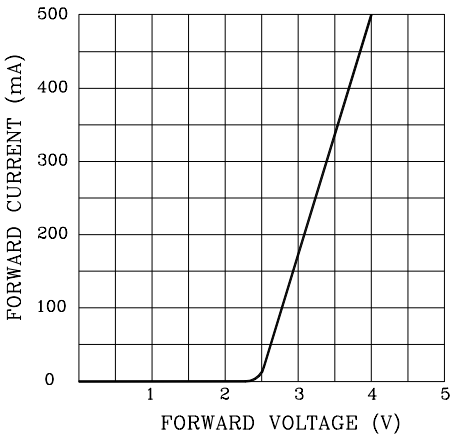


Fig.4 RELATIVE LUMINOUS INTENSITY VS. JUNCTION TEMPERATURE

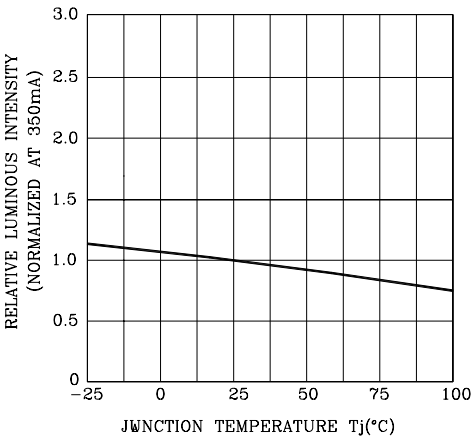


Fig.5 RELATIVE LUMINOUS INTENSITY VS. FORWARD CURRENT

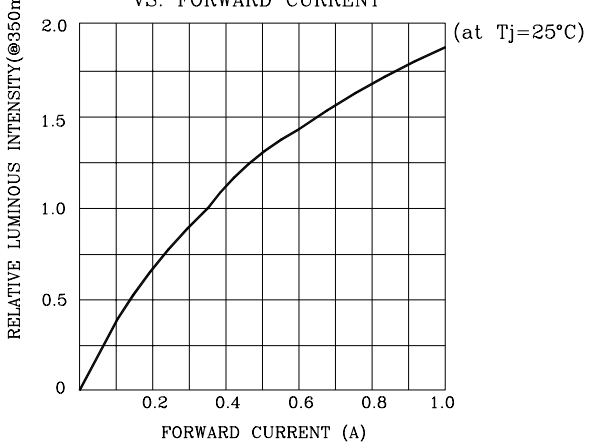
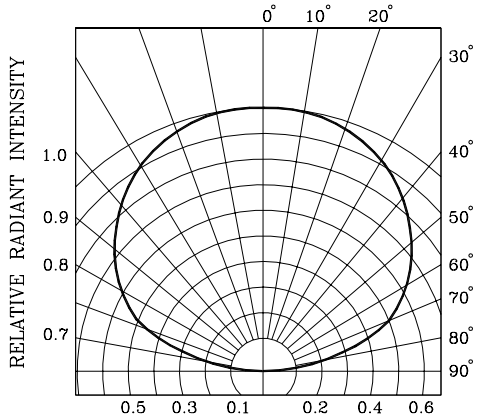
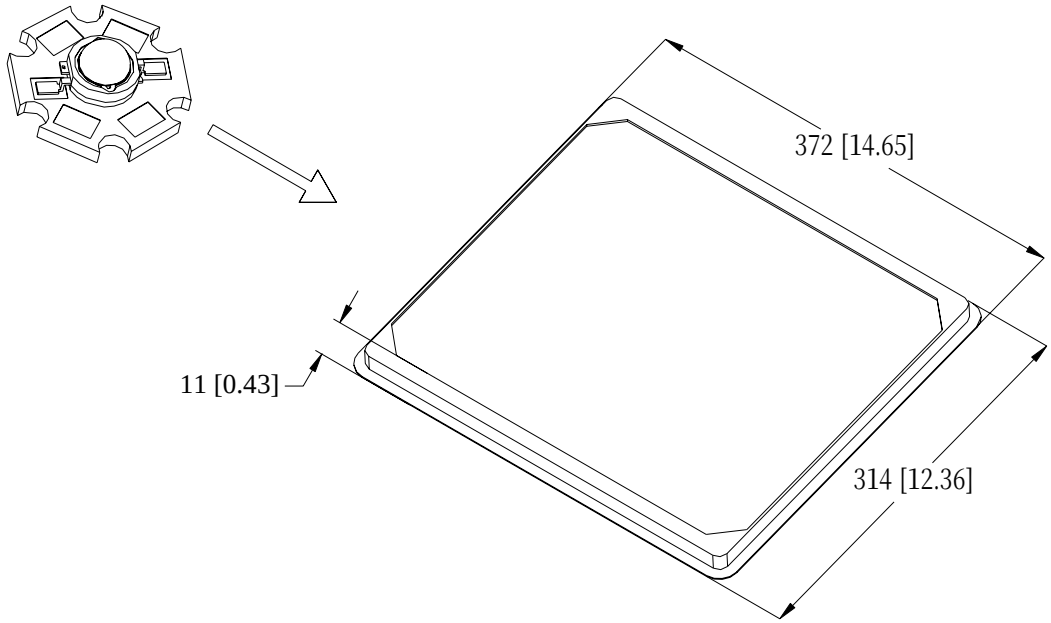


Fig.6 RADIATION DIAGRAM

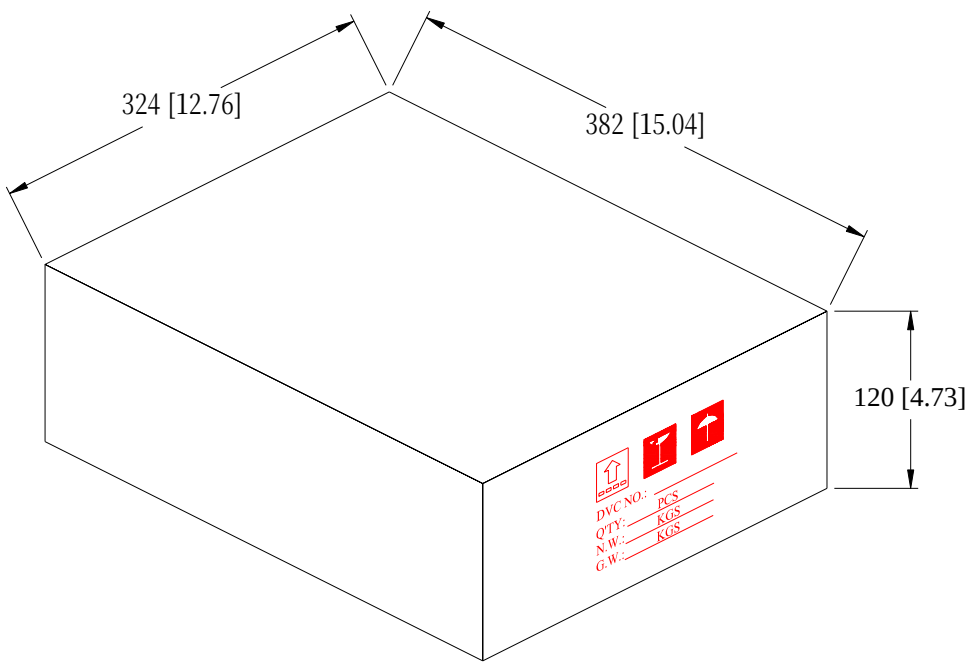


Package Method : (unit:mm)



80 pcs/tray

Tray



10 tray / carton

Carton

NOTES : Tray : Tolerance is ± 5 mm unless otherwise noted.
Carton : Tolerance is ± 10 mm unless otherwise noted.

● Total Flux Bin Limits (At 350mA)

BIN CODE	Min. (lm)	Max. (lm)
K	25	33
L	33	42
M	42	55

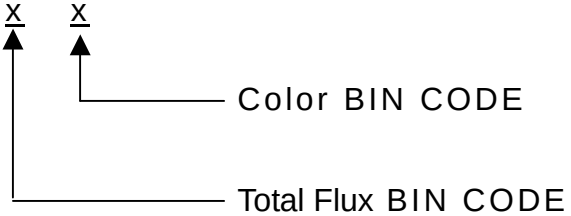
Tolerance for each Bin limit is ± 15 %

● Color Bin Limits(At 350mA)

BIN CODE	Min. (nm)	Max. (nm)
6	520	525
7	525	530

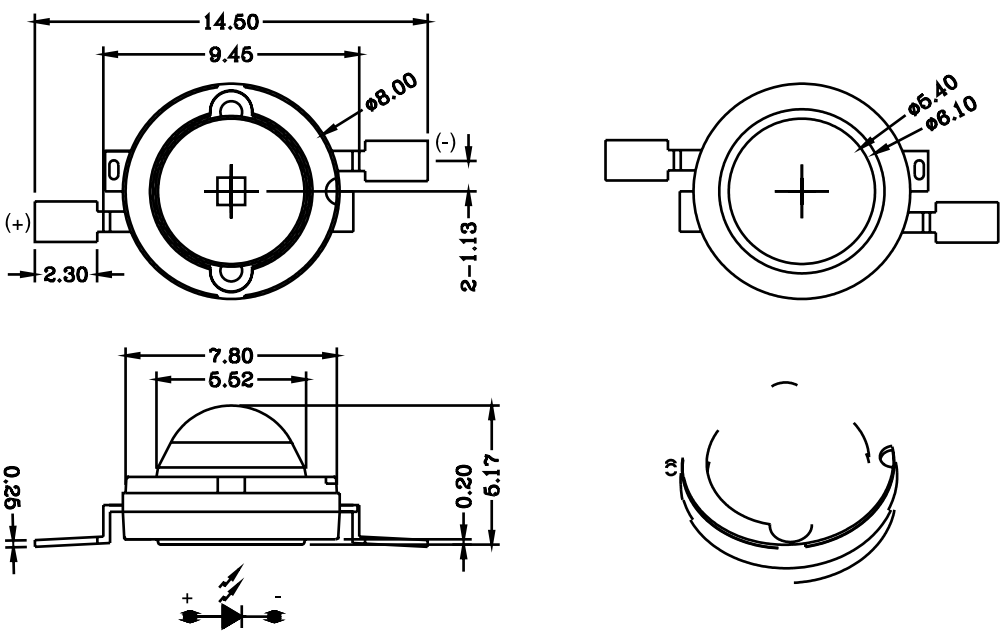
Tolerance for each Bin limit is ± 1 nm

● BIN：x x



Notes:

1. Bin categories are established for classification of products. Products may not be available in all bin categories.



Notes:

1. All dimensions are in millimeters.

2. Tolerance is ±0.5mm unless otherwise specified.

● Absolute maximum ratings (T_J=25℃)

Parameter	Symbol	Rating	Unit
Power Dissipation	P_D	1.4	W
DC Forward Current*[1]	I_F	700	mA
Peak Pulsed Forward Current*[2]	I_{FP}	1.5	A
LED Junction Temperature	T_J	125	°C
Operating Temperature	Topr	-30~110	°C
Storage Temperature	Tstg	-40~120	°C
Reverse Voltage	V_R	5	V
Soldering Temperature (T=5 sec)	Tsol	300 ± 5	°C

*[1]Proper current derating must be followed to keep LED junction temperature (T_J) below the maximum.

*[2]Condition for I_{FP} is pulsed with 1/10 duty and 0.1msec width.

● Electrical & Optical Characteristics (T_J=25℃)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	IF = 700mA	1.5	1.9	2.4	V
Radiant Power	Po	IF = 700mA	-	240	-	mW
Peak Wavelength	λp	IF = 700mA	-	850	-	nm
Spectral Line Half-width	$\Delta \lambda$	IF = 700mA	-	50	-	nm
Reverse Current	I_R	V_R =5V	-	-	50	μA
Rise/Fall Time PW=10uS DC=1%	Tr	I_{FP} =700mA	-	500	-	ns
Rise/Fall Time PW=10uS DC=1%	Tf	I_{FP} =700mA	-	200	-	ns
Thermal Resistance, Junction To Case	$R\theta_{J-C}$	IF = 700mA	-	15	-	℃/W
Viewing Angle	$2\theta_{1/2}$	IF = 700mA	-	120	-	degree

Typical electro-optical characteristics curves

Fig.1 RELATIVE INTENSITY VS. WAVELENGTH

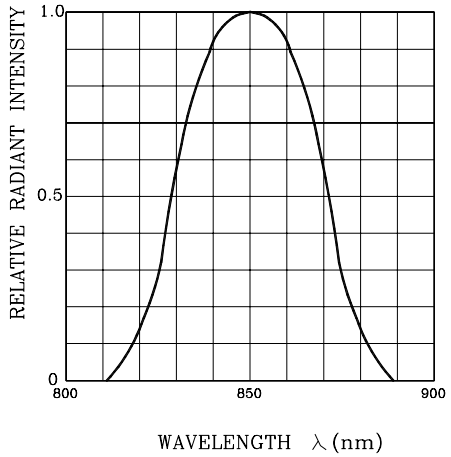


Fig.2 FORWARD CURRENT VS. AMBIENT TEMPERATURE

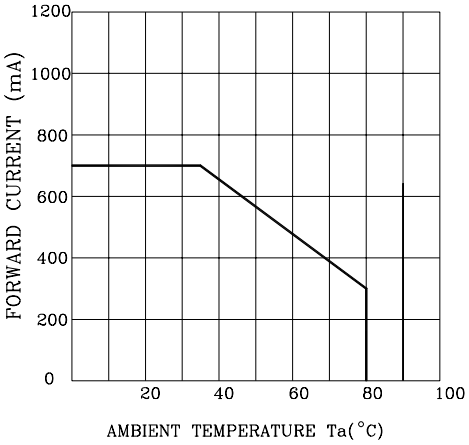


Fig.3 FORWARD CURRENT VS. FORWARD VOLTAGE

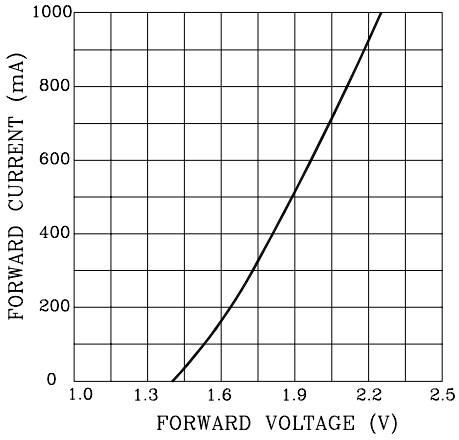


Fig.4 RELATIVE LUMINOUS INTENSITY VS. AMBIENT TEMPERATURE

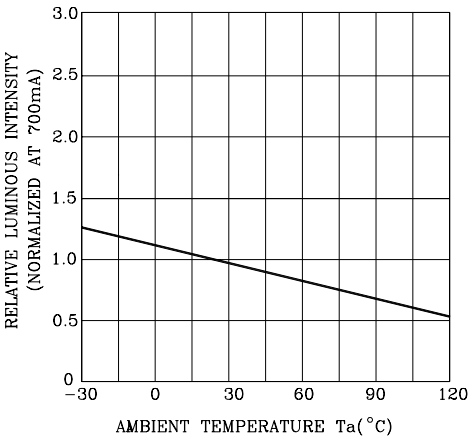


Fig.5 RELATIVE RADIANT POWER VS. FORWARD CURRENT

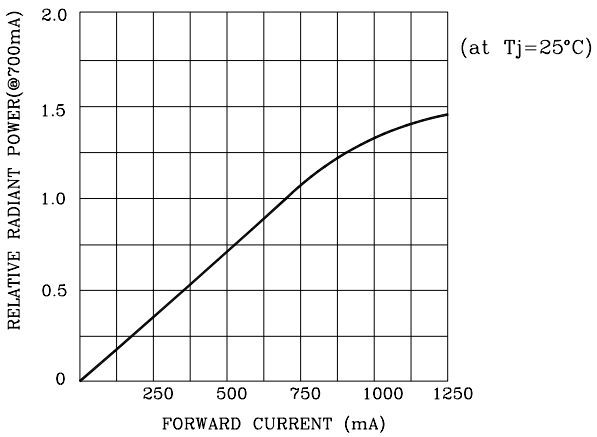
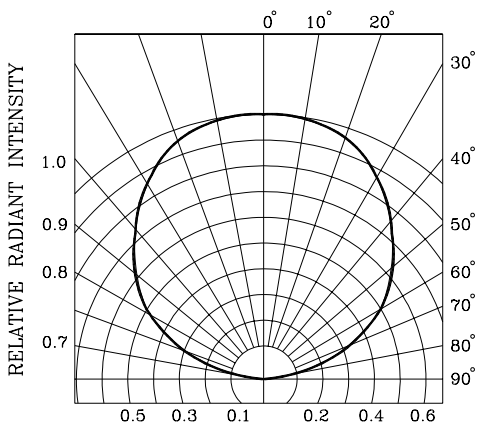
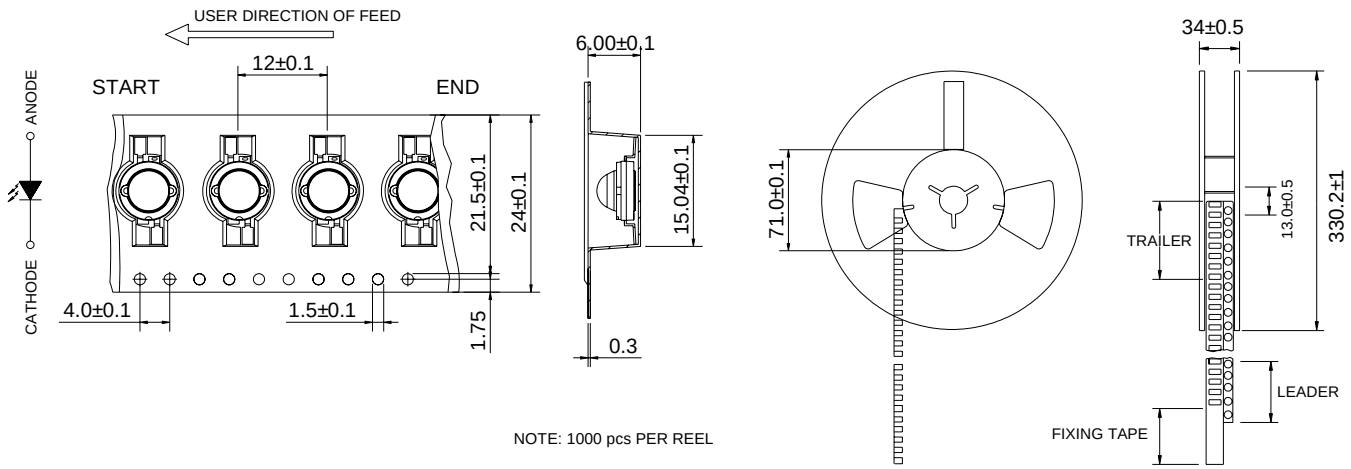


Fig.6 RADIATION DIAGRAM

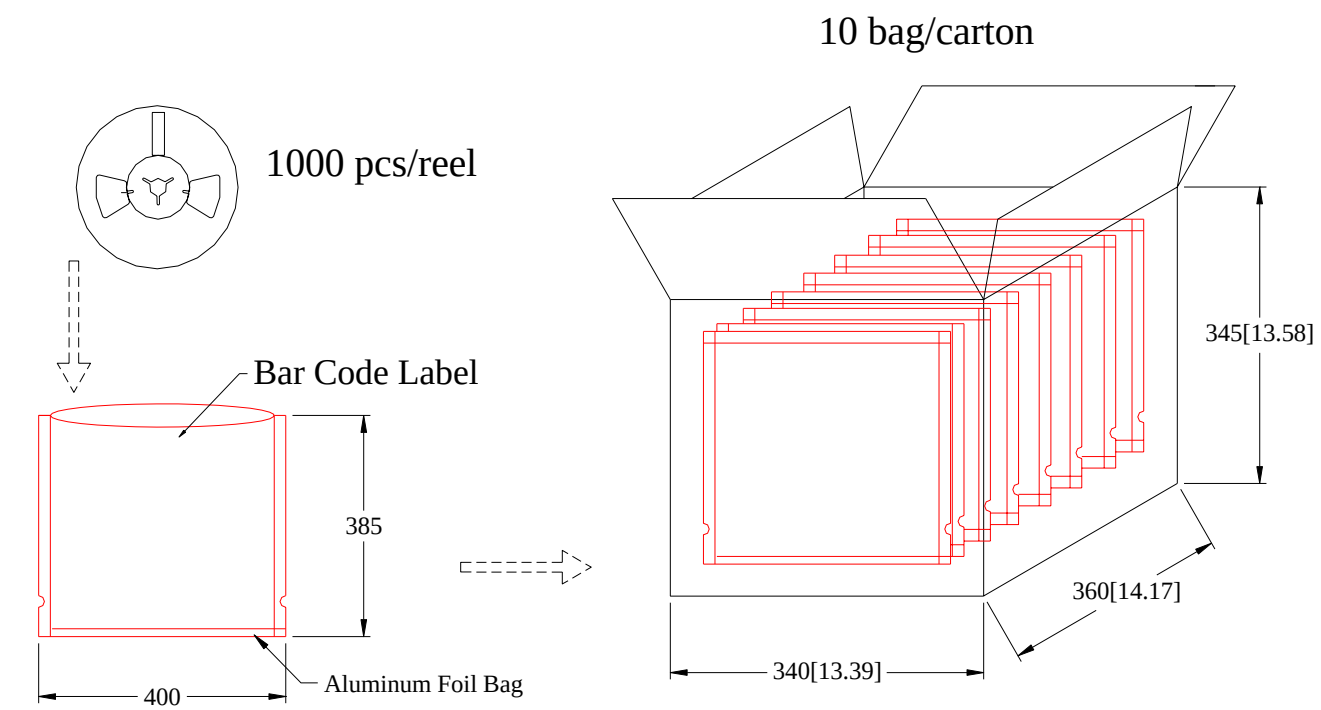


● Tapping and packaging specifications(Units: mm)



NOTE: 1000 pcs PER REEL

● Package Method : (unit:mm)



NOTES : Bag : Tolerance is ± 5 mm unless otherwise noted.
Carton : Tolerance is ± 10 mm unless otherwise noted.